

Features Include:

- Manufactured of Aluminum or Copper Alloys
- Anodized or Powder Coat Finish (special colors upon request)
- Plate Fin or Cross-Cut (Tight or Loose) Pin Configurations
- Any footprint ranging from 17~50mm or height from 10~40mm
- Optional Thermal Tape (consult Cofan for other mounting options)

Cofan's Passive BGA Heat Sinks are high efficiency cooling products designed to cool today's leading edge processor and memory chip applications. Our passive heat sinks are manufactured of aluminum or copper alloys with plate fin or cross-cut (tight or loose) fin configurations to best suit your environment.

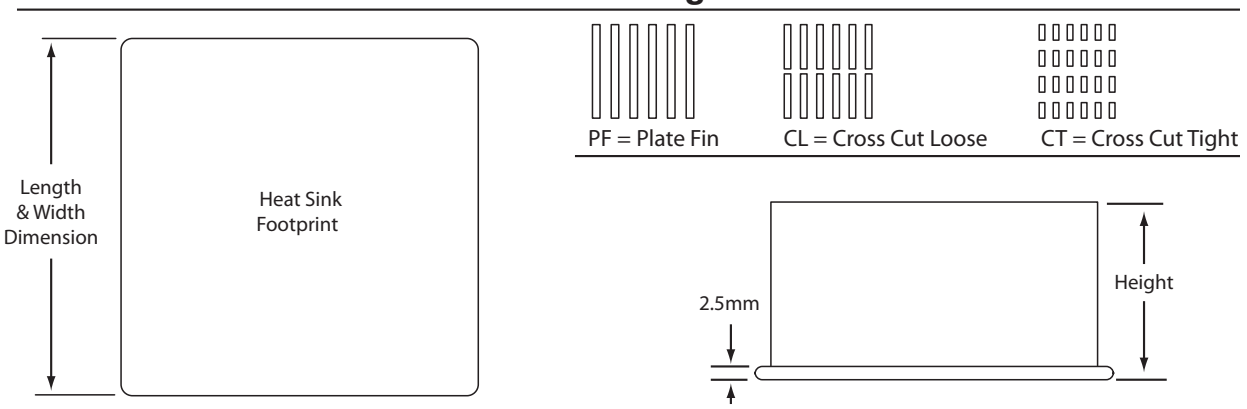
Part Number Configuration Guide:

>4,000 Models + Optional Thermal Tape

AL	01	PF	31	25	T
ALLOY= AL = ALUMINUM CU = COPPER	FINISH 01 = Clear Anodized 02 = Black Powder Coat	PIN / FIN TYPE: PF = PLATE FIN CL=CROSS CUT LOOSE CT= CROSS CUT TIGHT	SQUARE FOOTPRINT (mm) 17 = 17mm 33 = 33mm 19 = 19mm 35 = 35mm 21 = 21mm 38 = 37.5mm 23 = 23mm 40 = 40mm 25 = 25mm 43 = 42.5mm 27 = 27mm 45 = 45mm 29 = 29mm 48 = 47.5mm 31 = 31mm 50 = 50mm	HEIGHT (mm) 10 = 10mm 28 = 27.5mm 13 = 12.5mm 30 = 30mm 15 = 15mm 33 = 32.5mm 18 = 17.5mm 35 = 35mm 20 = 20mm 38 = 37.5mm 23 = 22.5mm 40 = 40mm 25 = 25mm	THERMAL PAD BLANK = NONE T =THERMAL PAD

* For detailed drawing of each unique model, check with our engineering team.

Heat Sink Configurations

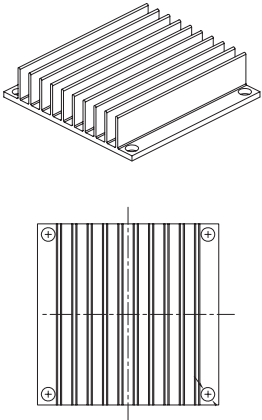


Consult with us for mounting accessories or spring-loaded mounting flanges / tabs

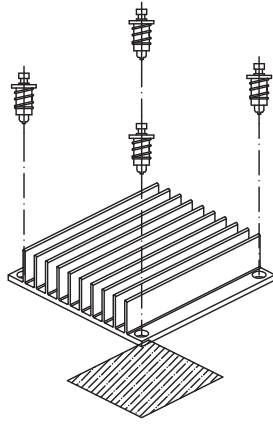
Various Mounting Options:

Below are just a few examples from our extensive library of mounting methods utilized in applications ranging from standard ITE to ruggedized / military environments.

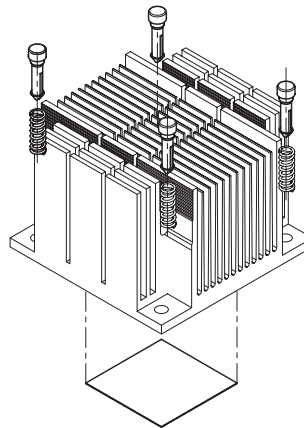
Simple Flange:



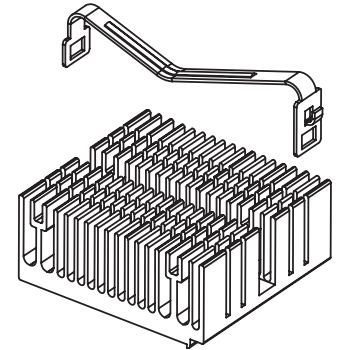
With Screws:



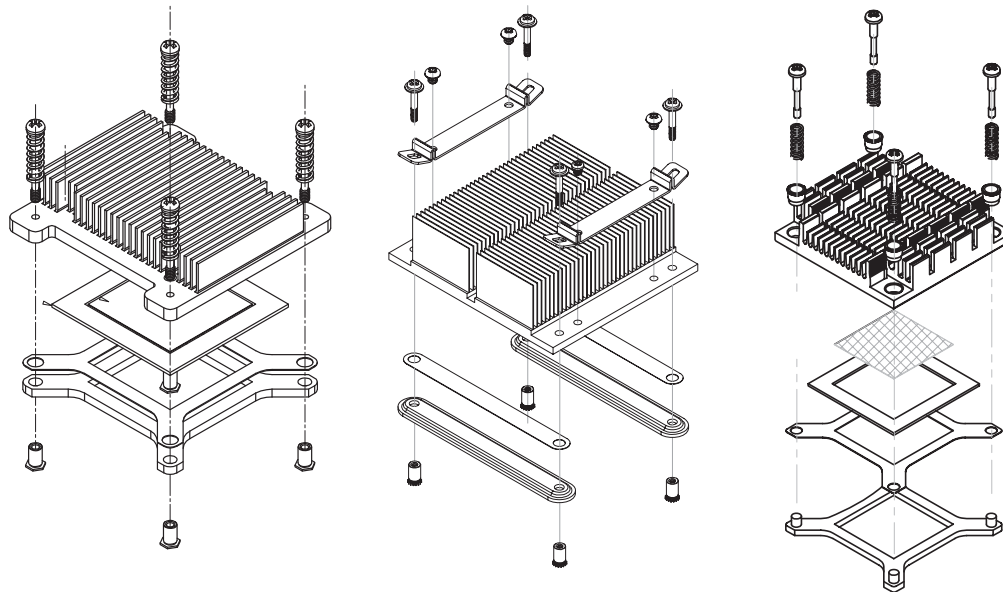
Spring-loaded Pins:



With Clip:



Ruggedized Applications:



What do you need?

**Call to discuss
your specific
application:**

(800)-766-6097